Full Material Declaration for attached parts list

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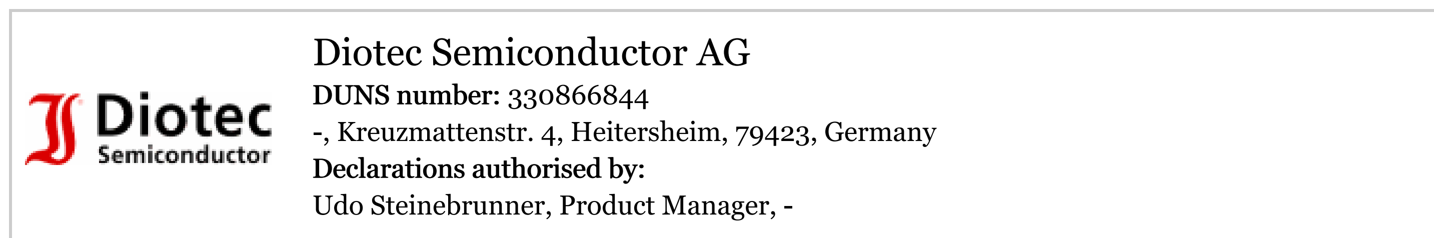

Diotec Semiconductor AG
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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 19 October 2022 [Approved on 23 February 2026, 14:14 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.88%	Silicon	7440-21-3	100%
Die attach	Sn-Pb solder	4.37%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	44.78%	Carbon black	1333-86-4	0.1%
			Magnesium oxide (Mg(OH)2)	1309-42-8	5%
			Phenol, polymer with formaldehyde	9003-35-4	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
			Quartz (SiO2) Exempt from other regulatory requirements	14808-60-7	79.9%
Leadfinish	Tin plating	0.55%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	46.42%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-123FL (H) H-free	Diode SMD	0.0183	g